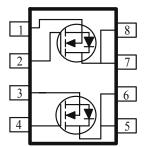
Dual N-Channel 30-V (D-S) MOSFET

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low $r_{DS(on)}$ and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

PRODUCT SUMMARY				
V _{DS} (V)	$r_{\mathrm{DS}(\mathrm{on})} \mathrm{m}(\Omega) \qquad \qquad I_{\mathrm{D}} (A)$			
30	$58 @ V_{GS} = 4.5V$	5.0		
	$82 @ V_{GS} = 2.5V$	4.2		

- Low r_{DS(on)} provides higher efficiency and extends battery life
- Low thermal impedance copper leadframe SOIC-8 saves board space
- Fast switching speed
- High performance trench technology





ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C UNLESS OTHERWISE NOTED)					
Parameter			Limit	Units	
Drain-Source Voltage			30	V	
Gate-Source Voltage			± 12	V	
	$T_A=25^{\circ}C$	т	5.0		
Continuous Drain Current ^a	$T_A=25^{\circ}C$ $T_A=70^{\circ}C$	1D	4.1	Α	
Pulsed Drain Current ^b			± 30		
Continuous Source Current (Diode Conduction) ^a			1.7	A	
D	$T_A=25^{\circ}C$	D	2.1	W	
Power Dissipation ^a	$T_A=25^{\circ}C$ $T_A=70^{\circ}C$	L D	1.3		
Operating Junction and Storage Temperature Range			-55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Maximum	Units		
M . I	t <= 10 sec	D	62.5	°C/W		
Maximum Junction-to-Ambient ^a	Steady State	$R_{\theta JA}$	80	°C/W		

1

Notes

- a. Surface Mounted on 1" x 1" FR4 Board.
- b. Pulse width limited by maximum junction temperature

SPECIFICATIONS (T _A = 25°C UNLESS OTHERWISE NOTED)							
Parameter	Cymbal	Test Conditions	Limits			T 124	
rarameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static							
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \text{ uA}$	0.7				
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			±100	nA	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55^{\circ}\text{C}$			25	uA	
On-State Drain Current ^A	$I_{D(on)}$	$V_{DS} = 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	20			A	
Durin Granes On Braintan A		$V_{GS} = 4.5 \text{ V}, I_D = 5 \text{ A}$			58	mΩ	
Drain-Source On-Resistance ^A	$r_{DS(on)}$	$V_{GS} = 2.5 \text{ V}, I_D = 4.2 \text{ A}$			82	1115.2	
Forward Tranconductance ^A	g_{fs}	$V_{DS} = 15 \text{ V}, I_{D} = 5 \text{ A}$		22		S	
Diode Forward Voltage	V_{SD}	$I_S = 1.7 \text{ A}, V_{GS} = 0 \text{ V}$		0.7		V	
Dynamic ^b							
Total Gate Charge	Q_{g}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V},$ $I_D = 5 \text{ A}$		6.3		nC	
Gate-Source Charge	Q_{gs}			0.9			
Gate-Drain Charge	Q_{gd}			1.9			
Input Capacitance	C_{iss}			257			
Output Capacitance	C_{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{MHz}$		62		pF	
Reverse Transfer Capacitance	C_{rss}			30			
Turn-On Delay Time	$t_{d(on)}$			22			
Rise Time	$t_{\rm r}$	$V_{DD} = 15 \text{ V}, R_L = 15 \Omega, I_D = 1 \text{ A},$		40		nS	
Turn-Off Delay Time	$t_{d(off)}$	$V_{GEN} = 4.5 \text{ V}$		50		113	
Fall-Time	t_{f}			20			

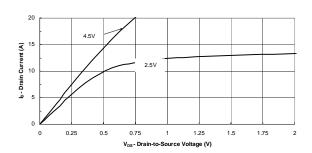
Notes

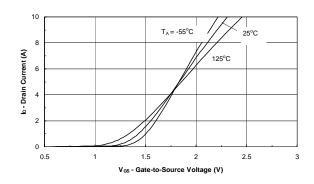
a. Pulse test: $PW \le 300us duty cycle \le 2\%$.

b. Guaranteed by design, not subject to production testing.

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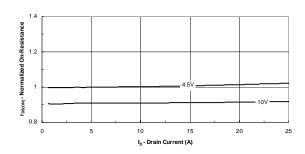
Typical Electrical Characteristics (N-Channel)

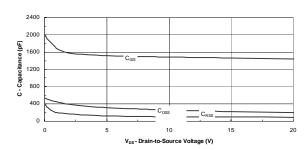




Output Characteristics

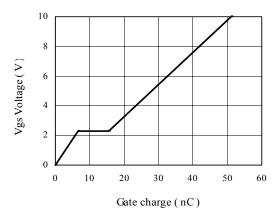
Transfer Characteristics

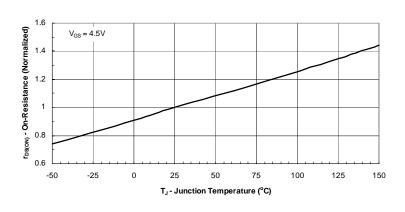




On-Resistance vs. Drain Current

Capacitance

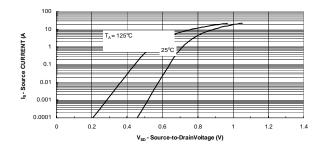


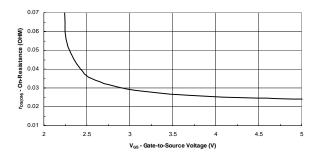


Gate Charge

On-Resistance vs. Junction Temperature

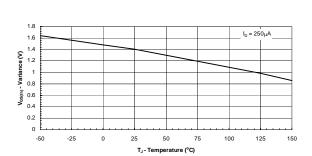
Typical Electrical Characteristics (N-Channel)



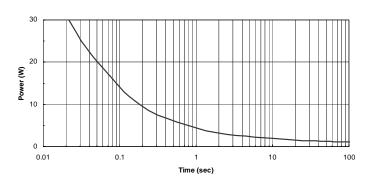


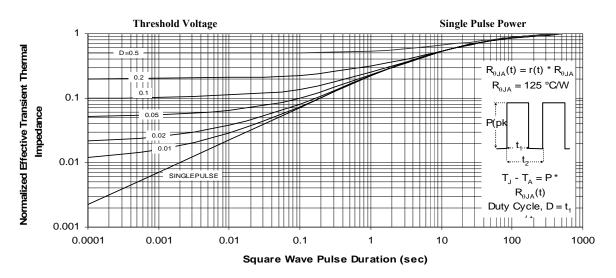
Source-Drain Diode Forward Voltage

aree Brain Bloue Forward Fortage



On-Resistance vs.Gate-to Source Voltage

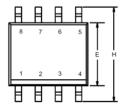


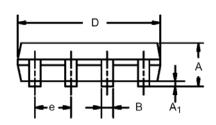


Normalized Thermal Transient Impedance, Junction-to-Ambient

Package Information

SO-8: 8LEAD





	MILLIM	IETERS	INCHES		
Dim	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27 BSC		0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	

